ABSTRACT

A raw sheet L, in which a strip-shaped tape base material TB having a die bonding sheet portion DS with a size of substantially corresponding to the shape of a semiconductor wafer W is temporarily stuck to a strip-shaped release liner S, is fed out, and a cut-line detecting device 14 detects whether any cut-line C is already formed on the outer circumference side of the die bonding sheet portion DS, on the pathway of the feeding out. According to the result of detection, the die cutting device 13 lets the raw sheet L pass straight through without forming any cut-line C when the cut-line C is judged to be already formed thereon. On the other hand, the die cutting device 13 forms a cut-line C to form a sticking tape DDT when no cut-line C is detected. The sticking tape DDT is peeled by a peeling device 15 to be stuck to the ring frame RF in the position that the die bonding sheet portion DS is to be corresponding to the semiconductor wafer W.